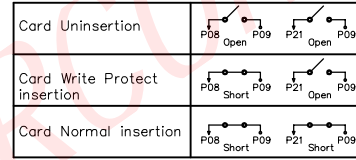
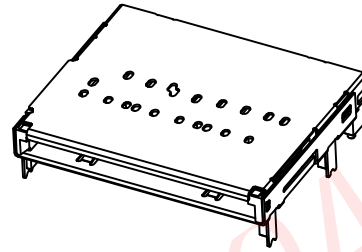
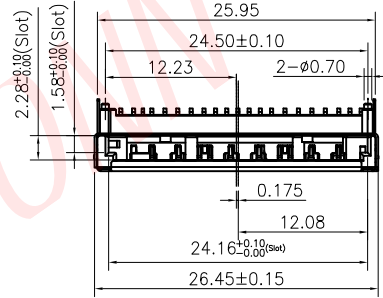
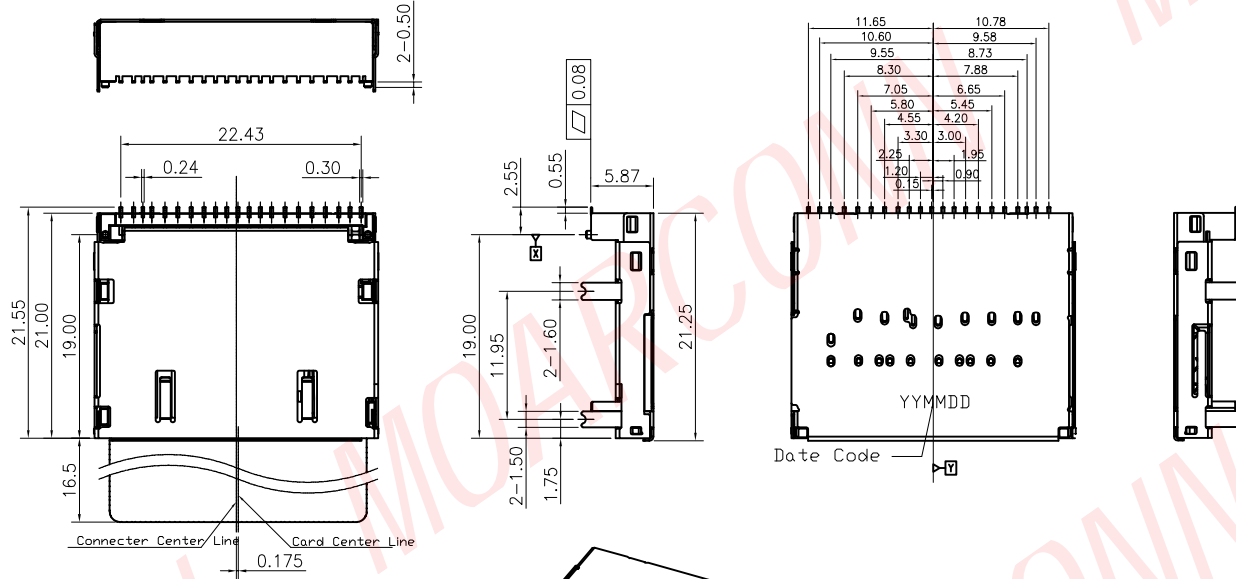
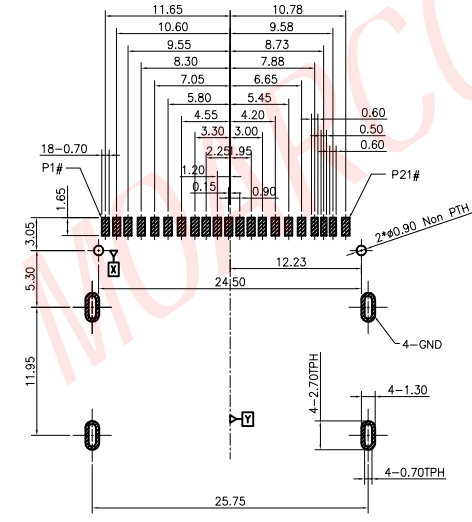


All materials, plating and process meet HF requirements.



PIN DEFINE:

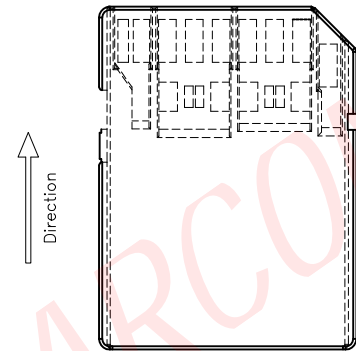
SD Mode		UHS-I Mode		SD Express Mode	
PIN#	NAME DESCRIPTION	PIN#	NAME DESCRIPTION	PIN#	NAME DESCRIPTION
1	VSS3 Supply voltage ground	1	VSS3 Supply voltage ground	1	VSS3 Supply voltage ground
2	RESERVED	2	RESERVED	2	RESERVED Reserved Area for future card insertion
3	DAT2 DATA LINE BIT2	3		3	CLKREQ# Reference clock request signal. Also used by L1 PM sub-states
4	DO+ DIFFERENTIAL DATE 0+	4	DO+ DIFFERENTIAL DATE 0+	4	PCie TX+
5	CD/DAT3 CARD DETECT/DATA LINE BIT3	5	NOT Used	5	PERST# PE-Reset is a functional reset
6	DO- DIFFERENTIAL DATE 0-	6	DO- DIFFERENTIAL DATE 0-	6	PCie TX-
7	CMD COMMAND/RESPONSE	7	NOT Used	7	NOT Used
8	CD CARD DETECT	8	CD CARD DETECT	8	CD CARD DETECT
9	VSS1 SUPPLY VOLTAGE GROUND	9	VSS1 Supply voltage ground	9	VSS1 Supply voltage ground
10	VSS4 SUPPLY VOLTAGE GROUND	10	VSS4 Supply voltage ground	10	VSS4 Supply voltage ground
11	VDD2 SUPPLY VOLTAGE	11	VDD2 Supply voltage(1.8V)	11	VDD2 Supply voltage(1.8V)
12	VDD SUPPLY VOLTAGE	12	VDD1 Supply voltage(3.3V)	12	VDD1 Supply voltage(3.3V)
13	D1- DIFFERENTIAL DATE 1-	13	D1- DIFFERENTIAL DATE 1-	13	PCie RX-
14	CLK CLOCK	14	NOT Used	14	NOT Used
15	D1+ DIFFERENTIAL DATE 1+	15	D1+ DIFFERENTIAL DATE 1+	15	PCie RX+
16	VSS2 SUPPLY VOLTAGE GROUND	16	VSS2 Supply voltage ground	16	VSS2 Supply voltage ground
17	VSS5 SUPPLY VOLTAGE GROUND	17	VSS5 Supply voltage ground	17	VSS5 Supply voltage ground
18	DAT0 DATA LINE BIT0	18	ROCK+	18	REFCLK+ PCie Ref CLOCK
19	DAT1 DATA LINE BIT1	19	ROCK-	19	VDD3 Supply voltage(1.2V)-TBD
20	DAT1 DATA LINE BIT1	20	ROCK-	20	REFCLK- PCie Ref CLOCK
21	WP WRITE PROTECT	21	WP WRITE PROTECT	21	WP WRITE PROTECT



Recommended PCB Layout
Top View(Tolerance±0.05)

Note:

- Material:
 - 1-1. Plastic: LCP, Black, UL94V-0
 - 1-2. Contact: Coper Alloy
 - 1-3. Shell: Stainless Steel
- Plating:
 - 2-1. Contact:
 - Contact Area: Au 1μ" min. Plating Over Ni 50μ" min.
 - Soldertail: Matte Tin 100μ" min. Plating Over Ni 50μ" min.
 - 2-2. Shell:
 - Solderability Ni 50μ" min. Over All
- Contact And Tail Coplanarity To Be 0.10mm max.



XO	----	NEW RELEASE	Aaron	2022.04.01
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

<p>MOARCONN MORE CONNECTIONS SMART FUTURE</p>		<p>DONG GUAN MOARCONN ELECTRONIC Co.,Ltd.</p>			
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NAME : SD7.0 BOTTOM H5.87 Non-push PRODUCT NO. : SD587-D1250-01 DRAWING NO. : D-SD587-D1250-01	DRAWING: Aaron CHECK: APPROVED: SCALE: 1:1 DWG ID: C D REV.: X0	DATE: 2022.04.01 DATE: DATE: PAGE: 1 OF 1